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PATENT
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IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Hifumi NAGAI et al. Conf.: 3883
Appl. No.: 09/931,406 Group: 1773
Filed: August 17, 2001 Examiner: Jackson
For: COPPER-ALLOY FOIL TO BE USED FOR LAMINATE SHEET

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

July 28, 2003

Sir:

In response to the Office Action mailed March 27, 2003, the period for response having been extended one month to expire on June 27, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

IN THE SPECIFICATION:

Please replace the paragraph beginning on page 4, lines 4-15, with the following rewritten paragraph:

--The peeling strength required for a printed circuit board is dependent upon the conditions of process and the environment in which the electronic machines are used. However, generally speaking, 5.0N/cm or more of 180° peeling strength is considered to enable practical application of the printed circuit board. Therefore, the target value of 180° peeling strength according to the present invention is 5.0N/cm or more. In addition, the target value of electrical conductivity is 50% IACS

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